

In the Specification:

Please amend Paragraph [0002] as follows:

[0002] This application ~~is related~~ claims priority to U.S. Provisional Application Serial No. 60/494,154 filed August 11, 2003, which application is incorporated herein by reference in its entirety.

Please amend Paragraph [0031] as follows:

[0031] Referring now to Figure 3a, after the development of the photosensitive material or photoresist 70, for example, in a tetramethylammonia ~~hydroxide~~ hydroxide (TMAH) solution, exposed portions 200 of the photoresist will be dissolved. Regions where the acid catalyst is depleted will dissolve to a lesser extent due to the suppression of the chemical amplification effect. This results in photoresist lines with a T-shaped top 210 being formed after development, as schematically shown in Figure 3a. Therefore, a consequence of the neutralization of the acid catalyst in the surface region of the photosensitive material is the formation of T-shaped lines with increased linewidth L_I .